

CRYSTAL OSCILLATOR (Programmable)

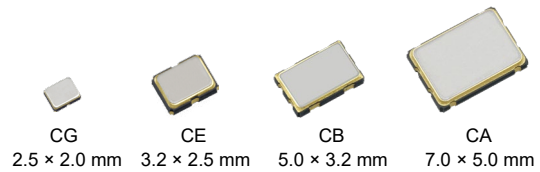
OUTPUT: CMOS

SG-8101 series

- Frequency range : 0.67 MHz to 170 MHz (1 × 10⁻⁶ Step)
- Supply voltage : 1.62 V to 3.63 V
- Function : Output enable (OE) or Standby (ST)
- Frequency tolerance : ±15 × 10⁻⁶ (-40 °C to +85 °C)
±20 × 10⁻⁶, ±50 × 10⁻⁶ (-40 °C to +105 °C)
- PLL technology to enable short lead time
- Available field oscillator programmer "SG-Writer II"



Product Number
 SG-8101CG: X1G005181xxxx00
 SG-8101CE: X1G005211xxxx00
 SG-8101CB: X1G005201xxxx00
 SG-8101CA: X1G005191xxxx00



Specifications (characteristics)

Item	Symbol	Specifications				Conditions/Remarks																																														
Supply voltage	V _{CC}	1.80 V Typ.		2.50 V Typ.	3.30 V Typ.		-																																													
		1.62 V to 1.98 V	1.98 V to 2.20 V	2.20 V to 2.80 V	2.70 V to 3.63 V																																															
Output frequency range	f _o	0.67 MHz to 170 MHz																																																		
Storage temperature range	T _{stg}	-40 °C to +125 °C				Storage as single product.																																														
Operating temperature range	T _{use}	-40 °C to +85 °C				-																																														
		-40 °C to +105 °C																																																		
Frequency tolerance ^{*1}	f _{tol}	B: ±15 × 10 ⁻⁶				T _{use} = -40 °C to +85 °C																																														
		C: ±20 × 10 ⁻⁶				T _{use} = -40 °C to +105 °C																																														
		J: ±50 × 10 ⁻⁶				T _{use} = -40 °C to +105 °C																																														
Current consumption	I _{CC}	3.2 mA Max.	3.3 mA Max.	3.4 mA Max.	3.5 mA Max.	T _{use} = +105 °C	No load, f _o = 20 MHz																																													
		2.7 mA Typ.		2.9 mA Typ.	3.0 mA Typ.	T _{use} = +25 °C																																														
		5.5 mA Max.	5.8 mA Max.	6.7 mA Max.	8.1 mA Max.	T _{use} = +105 °C	No load, f _o = 170 MHz																																													
		4.7 mA Typ.		5.7 mA Typ.	6.8 mA Typ.	T _{use} = +25 °C																																														
Output disable current	I _{dis}	3.2 mA Max.	3.2 mA Max.	3.3 mA Max.	3.5 mA Max.	OE = GND, f _o = 170 MHz																																														
Standby current	I _{std}	0.9 µA Max.	1.0 µA Max.	1.5 µA Max.	2.5 µA Max.	T _{use} = +105 °C																																														
		0.3 µA Typ.	0.4 µA Typ.	0.5 µA Typ.	1.1 µA Typ.	T _{use} = +25 °C																																														
Symmetry	SYM	45 % to 55 %				50 % V _{CC} Level																																														
Output voltage (DC characteristics)	V _{OH}	90 % V _{CC} Min.				<table border="1"> <thead> <tr> <th></th> <th colspan="5">[mA]</th> </tr> <tr> <th>Rise/Fall time</th> <th>V_{CC}</th> <th>*A</th> <th>*B</th> <th>*C</th> <th>*D</th> </tr> </thead> <tbody> <tr> <td rowspan="2">Default (f_o > 40 MHz)</td> <td>I_{OH}</td> <td>-2.5</td> <td>-3.5</td> <td>-4.0</td> <td>-5.0</td> </tr> <tr> <td>I_{OL}</td> <td>2.5</td> <td>3.5</td> <td>4.0</td> <td>5.0</td> </tr> <tr> <td rowspan="2">Default (f_o ≤ 40 MHz)</td> <td>I_{OH}</td> <td>-1.5</td> <td>-2.0</td> <td>-2.5</td> <td>-3.0</td> </tr> <tr> <td>I_{OL}</td> <td>1.5</td> <td>2.0</td> <td>2.5</td> <td>3.0</td> </tr> <tr> <td rowspan="2">Slow</td> <td>I_{OH}</td> <td>-1.0</td> <td>-1.5</td> <td>-2.0</td> <td>-2.5</td> </tr> <tr> <td>I_{OL}</td> <td>1.0</td> <td>1.5</td> <td>2.0</td> <td>2.5</td> </tr> </tbody> </table>			[mA]					Rise/Fall time	V _{CC}	*A	*B	*C	*D	Default (f _o > 40 MHz)	I _{OH}	-2.5	-3.5	-4.0	-5.0	I _{OL}	2.5	3.5	4.0	5.0	Default (f _o ≤ 40 MHz)	I _{OH}	-1.5	-2.0	-2.5	-3.0	I _{OL}	1.5	2.0	2.5	3.0	Slow	I _{OH}	-1.0	-1.5	-2.0	-2.5	I _{OL}	1.0	1.5	2.0	2.5
		[mA]																																																		
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	I _{OL}	1.0	1.5	2.0	2.5																																															
V _{OL}	10 % V _{CC} Max.																																																			
Output load condition	L _{CMOS}	15 pF Max.				-																																														
Input voltage	V _{IH}	70 % V _{CC} Min.				OE or ST																																														
	V _{IL}	30 % V _{CC} Max.																																																		
Rise time / Fall time	Default	tr/tf	3.0 ns Max.			f _o > 40 MHz																																														
			6.0 ns Max.			f _o ≤ 40 MHz																																														
			3.0 ns Max.			f _o = 0.67 MHz to 170 MHz																																														
			10.0 ns Max.			f _o = 0.67 MHz to 20 MHz																																														
Output disable time (OE)	tstp_oe	1 µs Max.				Measured from the time OE or ST pin crosses 30 % V _{CC}																																														
Output disable time (ST)	tstp_st	1 µs Max.				Measured from the time OE pin crosses 70 % V _{CC}																																														
Output enable time (OE)	tsta_oe	1 µs Max.				Measured from the time ST pin crosses 70 % V _{CC}																																														
Output enable time (ST)	tsta_st	3 ms Max.				Measured from the time V _{CC} reaches its rated minimum value, 1.62 V																																														
Start-up time	t _{str}	3 ms Max.				Measured from the time V _{CC} reaches its rated minimum value, 1.62 V																																														
Frequency aging	f _{age}	This is included in frequency tolerance specification.				+25 °C, first year																																														

*1 Frequency tolerance includes initial frequency tolerance, frequency / temperature characteristics, frequency / voltage coefficient, frequency / load coefficient and frequency aging (+25 °C, 1 year).

Pin description

Pin	Name	I/O type	Function	
1	OE	Input	Output enable	High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), only output driver is disabled.
	ST	Input	Standby	High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), Device goes to standby mode. Supply current reduces to the least as I _{std} .
2	GND	Power	Ground	
3	OUT	Output	Clock output	
4	V _{CC}	Power	Power supply	

*2 Please do not use the OE/ST terminal in the open state.



Product Name

SG-8101CG 25.000000MHz TCHPA
① ② ③ ④⑤⑥⑦⑧

- ① Model ② Package type
- ③ Frequency ④ Supply voltage (T: 1.8 V to 3.3 V Typ.)
- ⑤ Frequency tolerance ⑥ Operating temperature
- ⑦ Function ⑧ Rise/Fall time

② Package type	
CG	2.5 mm × 2.0 mm
CE	3.2 mm × 2.5 mm
CB	5.0 mm × 3.2 mm
CA	7.0 mm × 5.0 mm

⑤ Frequency tolerance / ⑥ Operating temperature	
BG	±15 × 10 ⁻⁶ / -40 °C to +85 °C
CH	±20 × 10 ⁻⁶ / -40 °C to +105 °C
JH	±50 × 10 ⁻⁶ / -40 °C to +105 °C

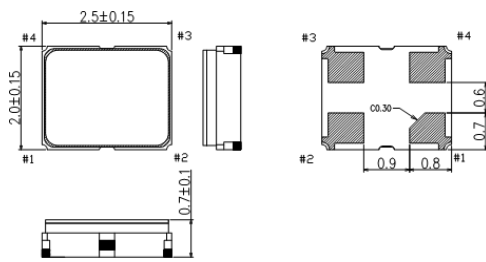
⑦ Function	
P	Output enable
S	Standby

⑧ Rise time/Fall time	
A	Default
B	Fast
C	Slow

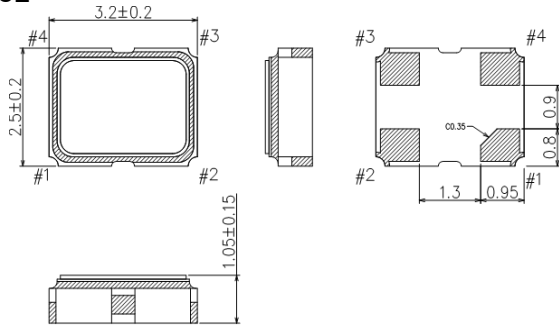
External dimensions

(Unit: mm)

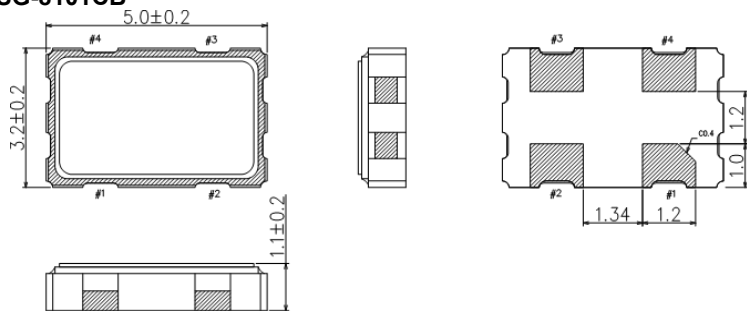
SG-8101CG



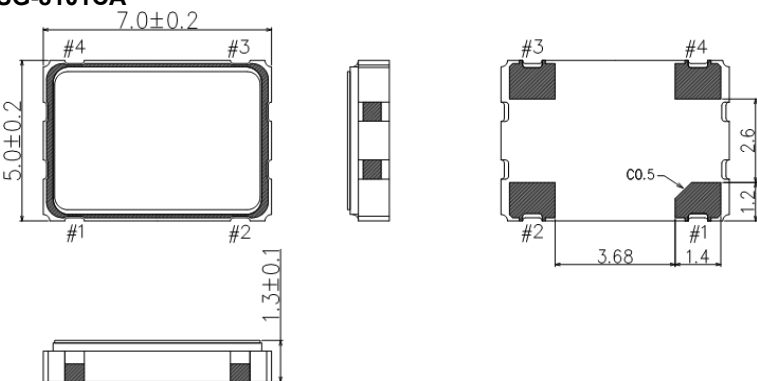
SG-8101CE



SG-8101CB



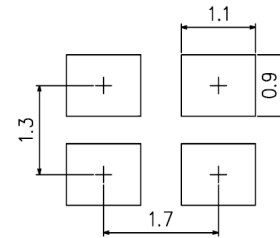
SG-8101CA



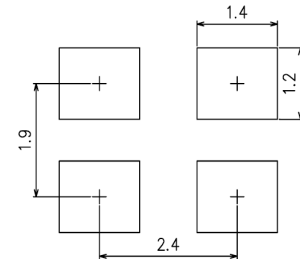
Footprint (Recommended)

(Unit: mm)

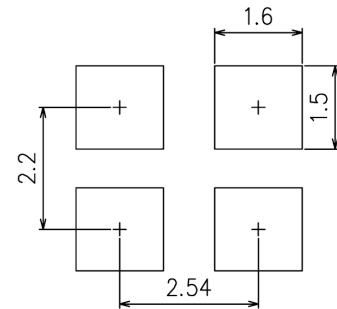
SG-8101CG



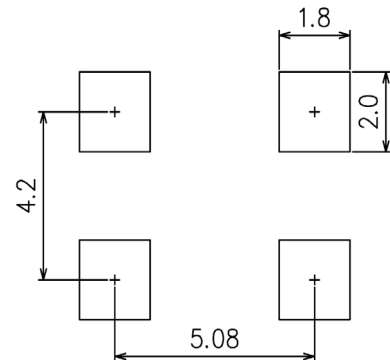
SG-8101CE



SG-8101CB







SG-8101CA



Notes:

In order to achieve optimum jitter performance, the 0.1 μF capacitor between V_{CC} and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

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	<p>► Pb free.</p>
	<p>► Complies with EU RoHS directive. *About the products without the Pb-free mark. Contains Pb in products exempted by EU RoHS directive. (Contains Pb in sealing glass, high melting temperature type solder or other.)</p>
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